

REMARKS

By this Amendment, claims 1, 13, 14 and 16 have been amended and new claims 17-23 have been added, all to further recite the claimed subject matter without the intention of narrowing any of the claims. Applicant does not, by this amendment, intend to abandon subject matter of the claims as originally filed or later presented. No new matter has been added. New claims 17-23 merely add dependent claims to the already pending independent claims 14, 15 and 16. Claims 1-23 are pending in this patent application. Reconsideration of the rejections in view of the remarks below is requested.

The Office Action summary does not reference whether the drawings were accepted. Applicant kindly requests an indication in the next action whether the drawings are acceptable.

The Office Action rejected claims 1-13, 15 and 16 under 35 U.S.C. §102(b) as being anticipated by U.S. patent no. 6,307,826 to Katsumura et al. ("Katsumura et al."). Applicant respectfully traverses the rejection, without prejudice.

Applicant respectfully submits that the cited portions of Katsumura et al. fail to disclose, teach or suggest a method of fabricating a device using a lithographic process comprising, *inter alia*, exposing a part of a resist layer on a substrate to ultraviolet radiation and applying an electric field across the resist, the direction of the field being substantially perpendicular to a plane of the resist layer during the exposing as recited in independent claim 1.

Katsumura et al. merely disclose an electron beam recorder for recording a master disc (e.g., a DVD) (Katsumura et al, col. 4, lines 44-45). Katsumura et al. however fail to disclose exposing a part of a resist layer on a substrate to ultraviolet radiation as recited in claim 1 since Katsumura et al. merely disclose exposing resist with an electron beam. Thus, the cited portions of Katsumura et al. fail to disclose, teach or suggest claim 1.

Further, Applicant respectfully submits that the cited portions of Katsumura et al. fail to disclose, teach or suggest a method of fabricating a device using a lithographic process comprising, *inter alia*, applying a radiation sensitive resist on top of the device, the resist material incorporating a conductive material as recited in independent claim 15.

The Office Action refers to col. 5, line 33 to col. 6, line 8 as disclosing the invention of claim 15. Applicant respectfully disagrees. Katsumura et al. merely disclose an ITO film 4b disposed over electron beam resist 4c wherein the ITO film 4b is set at the ground

potential of the electron beam recorder. However, Katsumura et al. fail to disclose, teach or suggest that the resist material itself incorporates a conductive material as recited in claim 15.

Applicant also respectfully submits that the cited portions of Katsumura et al. fail to disclose, teach or suggest a method of processing a device using a lithographic process wherein, *inter alia*, said device comprises a radiation sensitive and conductive resist material as recited in independent claim 16.

As discussed above, Katsumura et al. merely disclose an ITO film 4b disposed over electron beam resist 4c wherein the ITO film 4b is set at the ground potential of the electron beam recorder. However, Katsumura et al. fail to disclose, teach or suggest a radiation sensitive and conductive resist material as recited in claim 16.

Therefore, for at least the above reasons, the cited portions of Katsumura et al. fail to disclose, teach or suggest all the features recited by independent claims 1, 15 and 16. Claims 2-13 depend from independent claim 1 and are, therefore, patentable for at least the same reasons provided above related to claim 1, and for the additional features recited therein. Further, new claims 20-21 depend from independent claim 15 and are, therefore, patentable for at least the same reasons provided above related to claim 15, and for the additional features recited therein. Also, new claims 22-23 depend from independent claim 16 and are, therefore, patentable for at least the same reasons provided above related to claim 16, and for the additional features recited therein. As a result, Applicant respectfully submits that the rejection under 35 U.S.C. §102(b) of claims 1-13, 15 and 16 in view of Katsumura et al. should be withdrawn and the claims allowed.

The Office Action rejected claim 14 under 35 U.S.C. §102(e) as being anticipated by U.S. patent publication no. 2004/0256579 to Viscor et al. ("Viscor et al."). Applicant respectfully traverses the rejection, without prejudice.

Applicant respectfully submits that the cited portions of Viscor et al. fail to disclose, teach or suggest a lithographic apparatus comprising, *inter alia*, an illumination system configured to condition a projection beam of ultraviolet radiation as recited in independent claim 14.

Viscor et al. merely disclose a planar electron beam lithography system 100 that has a planar electron emitter (PEE) and an integrated mask unit 102 housed in a mask controller device 104. The electron beam 112 emanating from the planar electron emitter (PEE) and integrated mask unit 102 may be directed by a projection device 114 to image the mask features at a unity (one-to-one) magnification onto a resist surface of a wafer 116. (Viscor et

al., paragraphs [0025] – [0026]). Viscor et al. however fail to disclose an illumination system configured to condition a projection beam of ultraviolet radiation as recited in claim 14. Indeed, Viscor et al. teach away from using ultraviolet radiation and offer their planar electron beam lithography system as an alternative to lithography using ultraviolet radiation. (Viscor et al., paragraphs [0002] – [0005]).

Therefore, for at least the above reasons, the cited portions of Viscor et al. fail to disclose, teach or suggest all the features recited by independent claim 14. New claims 17-19 depend from independent claim 14 and are, therefore, patentable for at least the same reasons provided above regarding Viscor et al. as related to independent claim 14, and for the additional features recited in those dependent claims. As a result, Applicant respectfully submits that the rejection under 35 U.S.C. §102(e) of claim 14 in view of Viscor et al. should be withdrawn and the claims allowed.

All objections and rejections having been addressed, it is respectfully submitted that the present application is in condition for allowance. If questions relating to patentability remain, the Examiner is invited to contact the undersigned to discuss them.

Should any fees be due, please charge them to our deposit account no. 03-3975, under our order no. 081468/0309171. The Commissioner for Patents is also authorized to credit any over payments to the above-referenced deposit account.

Respectfully submitted,  
PILLSBURY WINTHROP SHAW PITTMAN LLP

A handwritten signature in black ink, appearing to read 'J. S. Barufka', is written over a horizontal line.

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